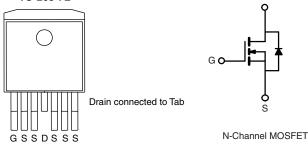


Automotive N-Channel 40 V (D-S) 175 °C MOSFET

D

PRODUCT SUMMARY				
V _{DS} (V)	40			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.0011			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.0013			
I _D (A)	200			
Configuration	Single			

TO-263-7L



FEATURES

- TrenchFET[®] Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_q and UIS Tested
- AEC-Q101 Qualified^d
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>



ORDERING INFORMATION	
Package	TO-263-7L
Lead (Pb)-free and Halogen-free	SQM200N04-1m1L-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current ^a	T _C = 25 °C	1	200		
	T _C = 125 °C	I _D	200		
Continuous Source Current (Diode Conduction) ^a		I _S	200	А	
Pulsed Drain Current ^b		I _{DM}	600		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	100		
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	500	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P	375	W	
	T _C = 125 °C	P _D	125		
Operating Junction and Storage Temperature F	lange	T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W
nction-to-Case (Drain)		R _{thJC}	0.4	0/10

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

SQM200N04-1m1L



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$		40	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		2.0	2.5		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA	
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V _{DS} = 40 V	-	-	1		
	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 40 V, T _J = 125 °C	-	-	50	μA	
		$V_{GS} = 0 V$	V _{DS} = 40 V, T _J = 175 °C	-	-	500		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	200	-	-	Α	
Drain-Source On-State Resistance ^a		V _{GS} = 10 V	I _D = 30 A	-	0.0008	0.0011	Ω	
		V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	-	0.0019		
	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 30 A, T _J = 175 °C	-	-	0.0023		
		$V_{GS} = 4.5 V$	I _D = 20 A	-	0.0009	0.0013		
Forward Transconductanceb	9 _{fs}	V _{DS}	= 15 V, I _D = 30 A	-	219	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}		V _{DS} = 25 V, f = 1 MHz	-	16 524	20 655	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	2060	2575		
Reverse Transfer Capacitance	C _{rss}	1		-	484	605		
Total Gate Charge ^c	Qg	V _{GS} = 10 V	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 20 \text{ A}$	-	275	413	nC	
Gate-Source Charge ^c	Q _{gs}			-	56.6	-		
Gate-Drain Charge ^c	Q _{gd}	1		-	45.4	-		
Gate Resistance	Rg	f = 1 MHz		4.2	8.5	12.8	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	13	20		
Rise Time ^c	t _r	$V_{DD} = 20 \text{ V}, \text{ R}_{L} = 1 \Omega$ $\text{I}_{D} \cong 20 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		-	12	18	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	443	665		
Fall Time ^c	t _f			-	126	189		
Source-Drain Diode Ratings and Char	acteristics ^b	<u> </u>				- -	·	
Pulsed Current ^a	I _{SM}			-	-	600	А	
Forward Voltage	V _{SD}	I _F = 60 A, V _{GS} = 0 V		-	0.8	1.5	V	

Notes

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

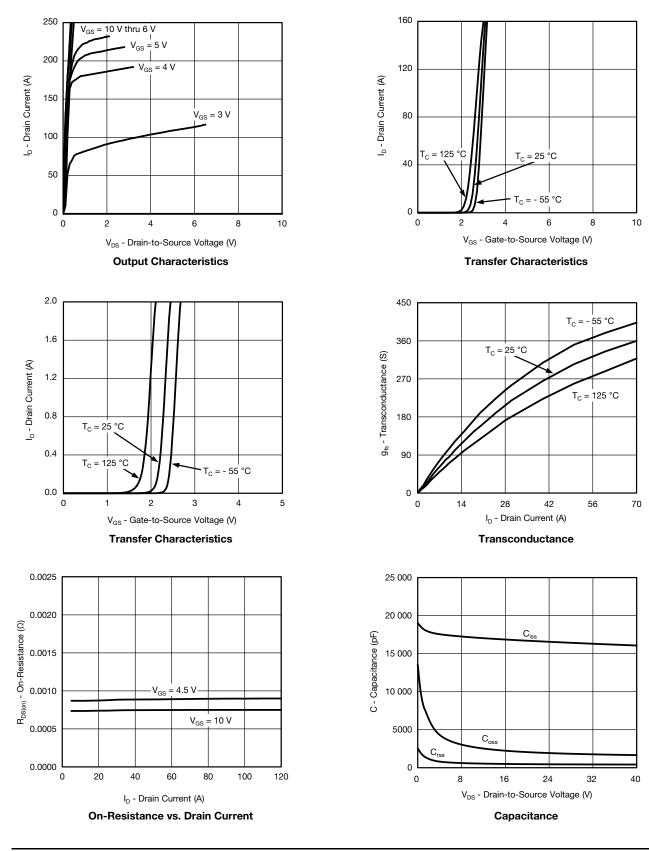
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

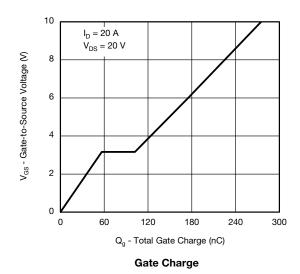


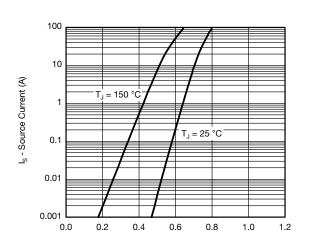
Document Number: 62679

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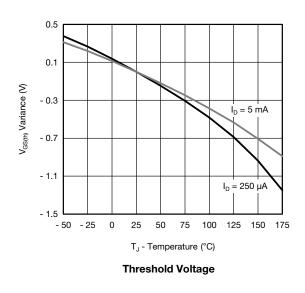


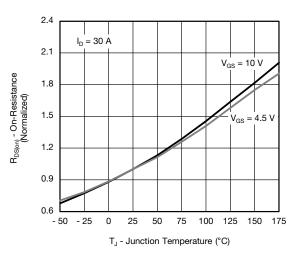
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



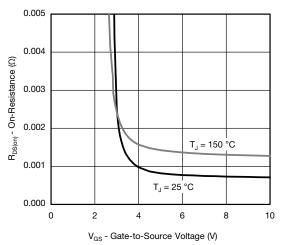


V_{SD} - Source-to-Drain Voltage (V) Source Drain Diode Forward Voltage

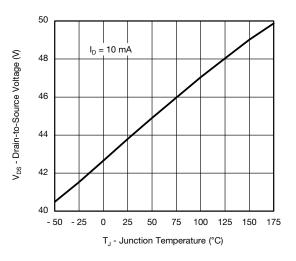




On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature

S12-2164-Rev. A, 24-Sep-12

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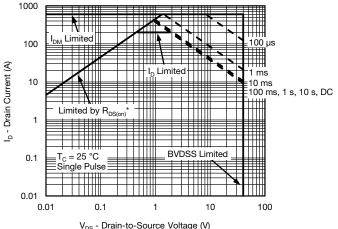
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SQM200N04-1m1L

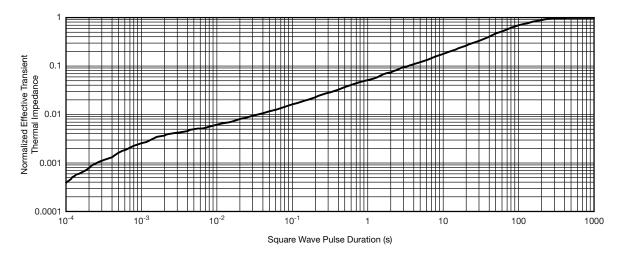
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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

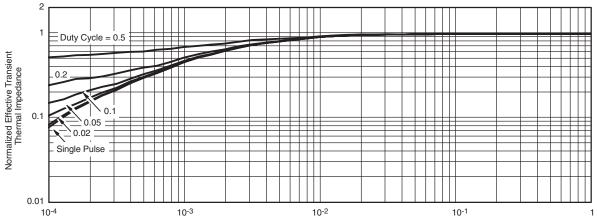




Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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